



VMDSEMI

VUTP003R031NA

Datasheet



VMDSEMI

General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
30V	3.1mΩ@10V	140A
	3.8mΩ@4.5V	

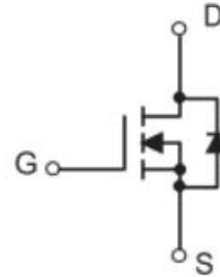
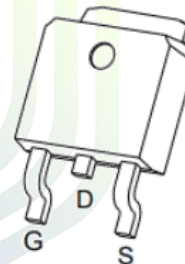


Figure 1 Symbol of VUTP003R031NA

Features

- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- Low $R_{DS(ON)}$
- 100% UIS Tested

Package Type

TO-263-2L
Application

- Power Switch Application
- DC/DC Converter

Figure 2 Package Type of VUTP003R031NA

Ordering Information

Product Name	Package
VUTP003R031NA	TO-263-2L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	$T_C = 25\text{ °C}$	140
Continuous Drain Current ^{Note1}		$T_A = 25\text{ °C}$	90
Pulsed Drain Current ^{Note2}	I_{DM}	560	A
Avalanche Current ^{Note3}	I_{AS}	53	A
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	702	mJ
Total Power Dissipation ^{Note5}	P_D	$T_C = 25\text{ °C}$	125
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.0		°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		2.5	3.1	mΩ
		$V_{GS}=4.5V, I_D=10A$		2.9	3.8	
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=10V, I_D=10A$	10			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=15V$		5144		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		721		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		688		pF
Total Gate Charge	Q_g	$V_{DS}=15V$		120		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		16		
Gate-Drain Charge	Q_{gd}	$I_D=20A$		37		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		1.0		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		18		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		22		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		52		
Turn-off Fall Time	t_f	$R_G=3\Omega$		20		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=25V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

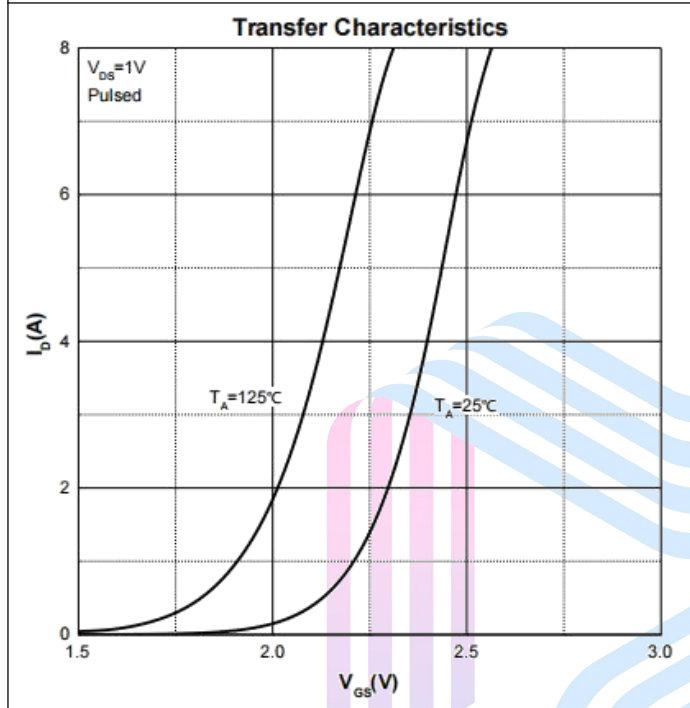


Figure 4: Output Characteristics

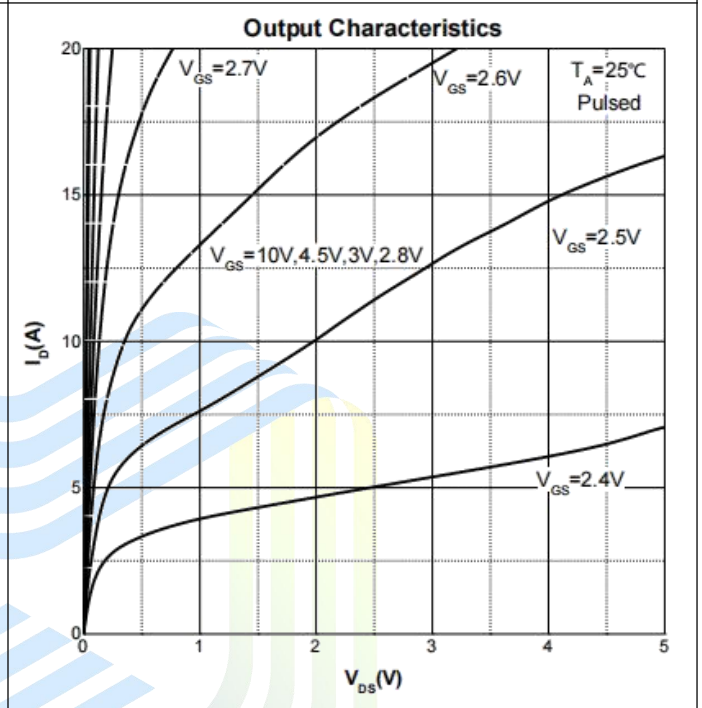


Figure 5: On-Resistance vs. Drain Current

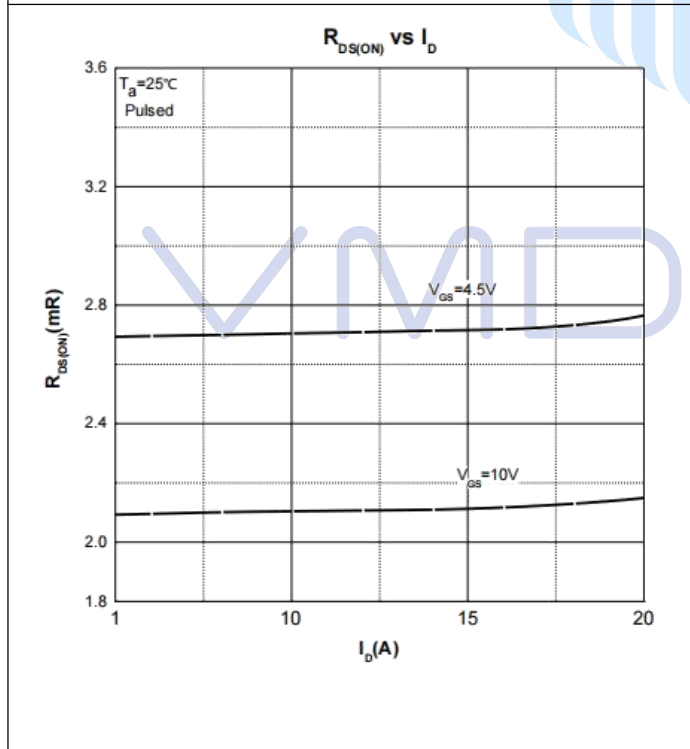


Figure 6: On-Resistance vs. Gate Voltage

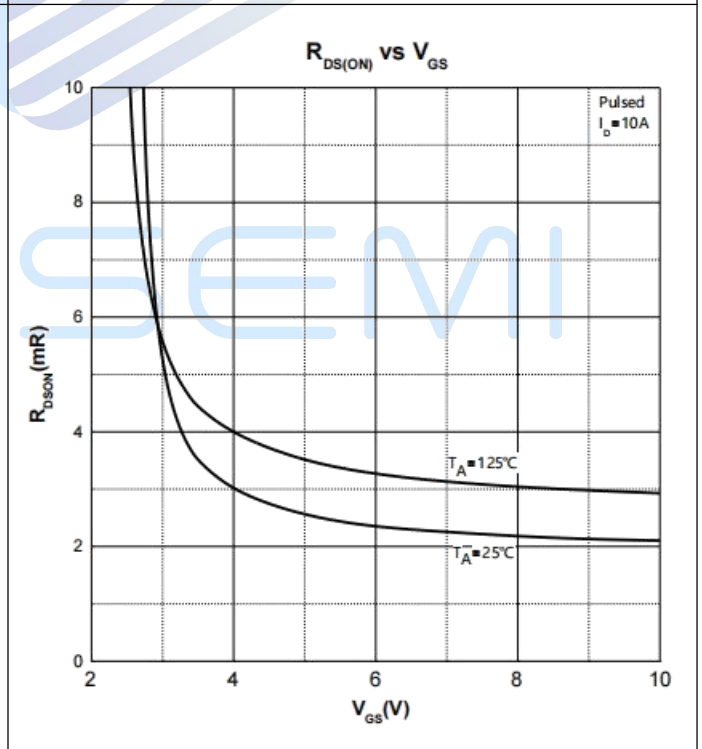


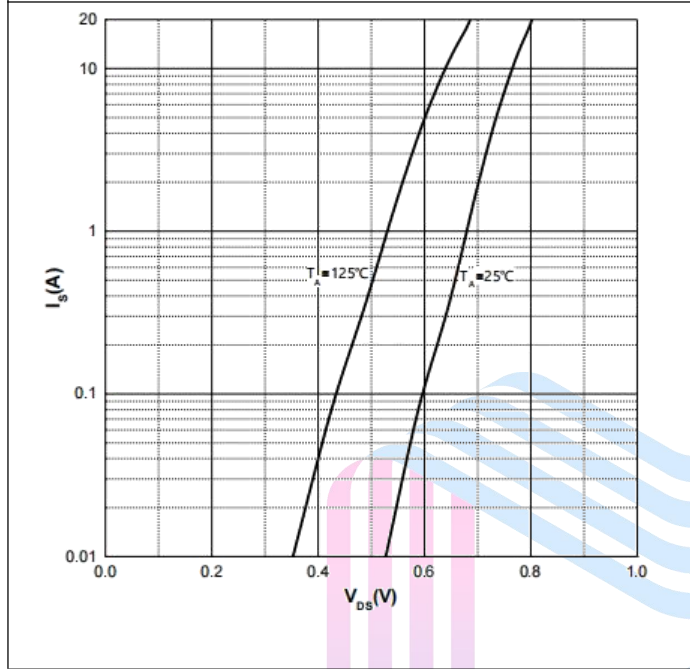
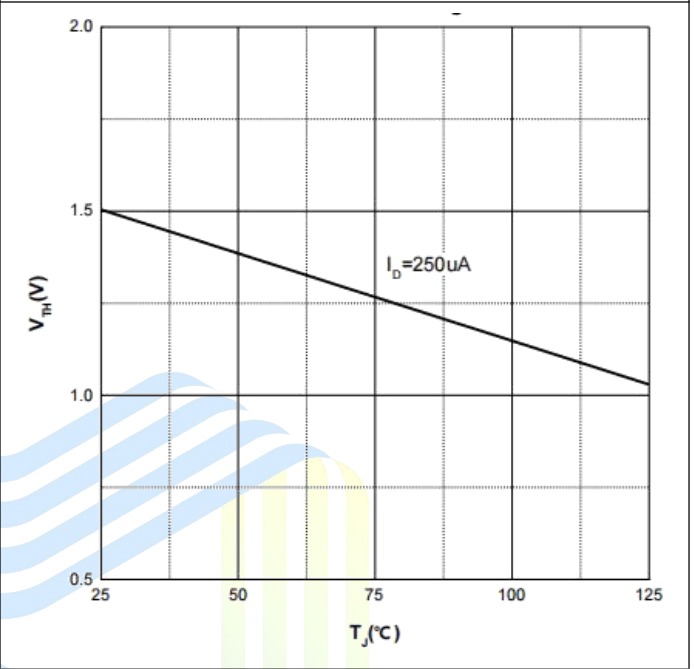
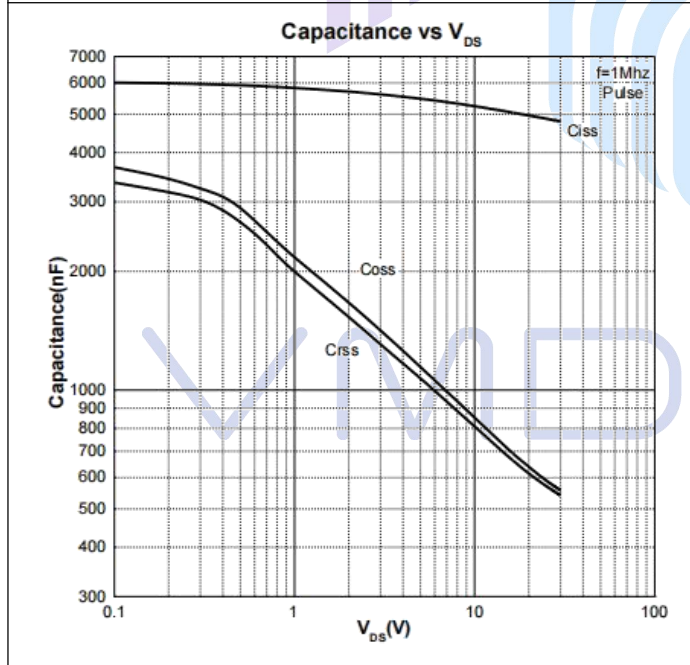
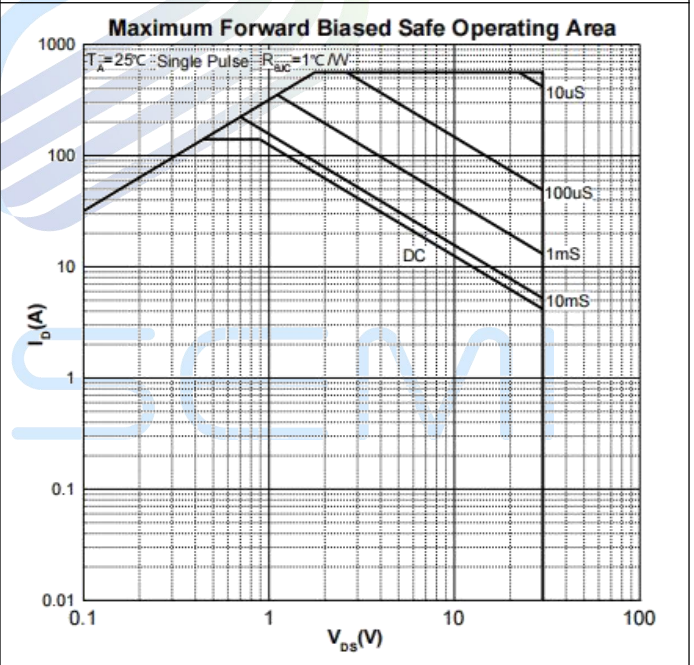
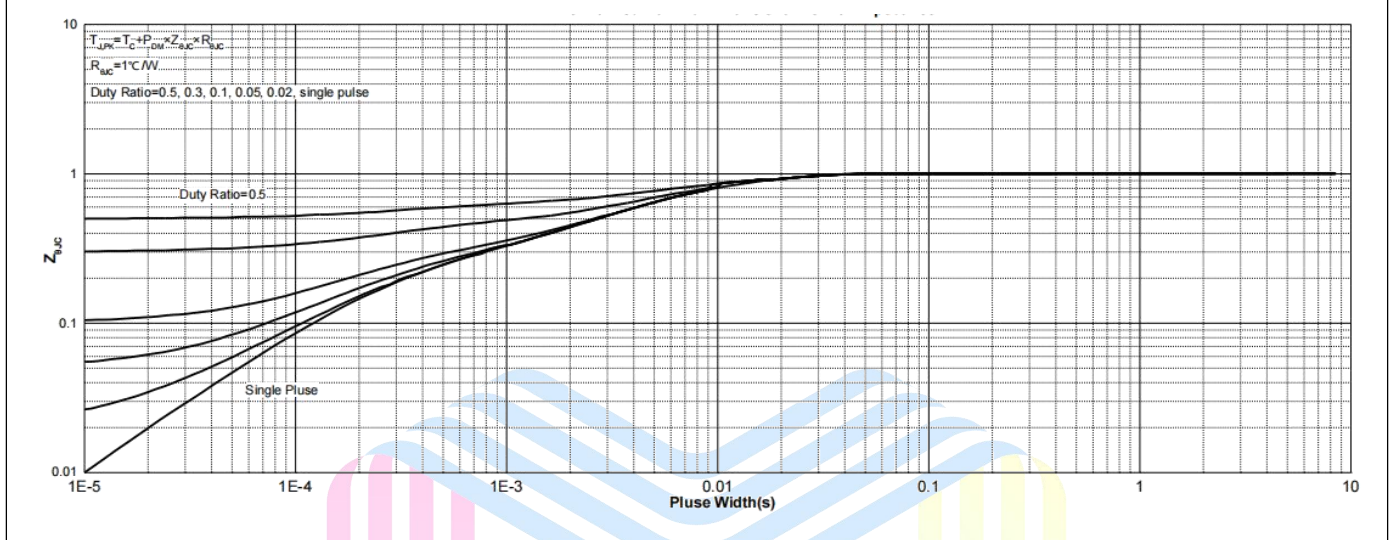
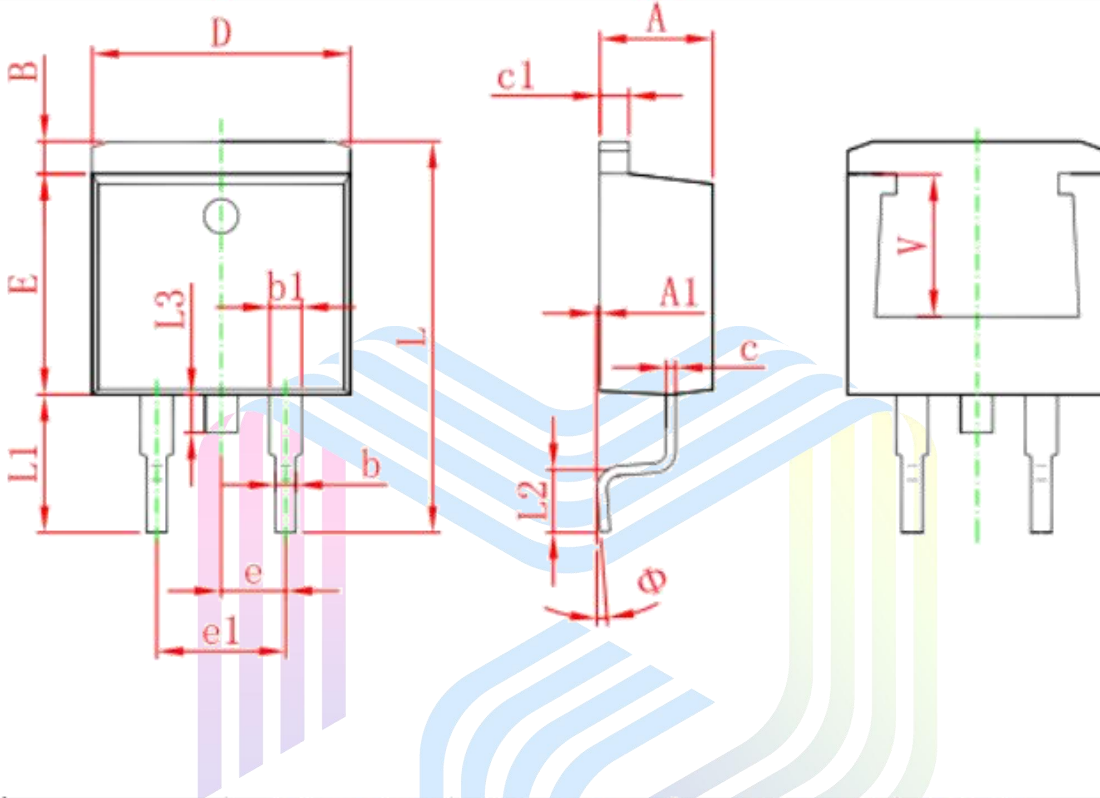
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operating Area


Figure 11: Normalized Maximum Transient Thermal Impedance


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Mechanical Dimensions:
TO-263-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	

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Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Shenzhen

Shenzhen Sales office
Room 4A15, Block AB, Tianxiang Building,
Chegongmiao , Futian District, Shenzhen, P.R of China
Tel: +86-0755- 82570682

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China